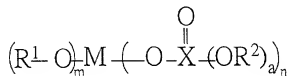


ABSTRACT OF THE DISCLOSURE

The present invention discloses a conductive composition, comprising: (a) at least one polymer; (b) at least one conductive filler, dispersed in the polymer; and (c) a coupling agent, applied to improved the adhesion between the polymer and the conductive filler and having a structure as follows:



wherein M represents a metal atom or silicon; R¹ and R² represent a substituted or unsubstituted alkyl group; X represents sulfur or phosphorous; and a, m and n represent integers of 0 to 2.